Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1659	438/118,119.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/06 08:44
L2	1599	257/782,783.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/06 08:45
L3	1729	219/603,616,635,651,673,677. ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/06 08:46
L4	1626	219/388.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/06 08:46
L5	702	228/42,46.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/06 08:46
L6	7118	1 2 3 4 5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/06 08:47
L7	1	(die chip wafer) with (mounting attached attach attachment bonding bonded) with (substrate carrer board) with (heating near1 conduit) with (moving movable move moved) with temperature with eutectic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/06 08:51
L8	1	(die chip wafer) same (mounting attached attach attachment bonding bonded) same (substrate carrer board) same (heating near1 conduit) same (moving movable move moved) same temperature same eutectic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/06 08:54

L9	1	(die chip wafer) same (mounting attached attach attachment bonding bonded) same (substrate carrer board) same (heating near1 conduit) same (moving movable move moved) same temperature	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/06 08:54
L10	1	(die chip wafer) same (mounting attached attach attachment bonding bonded) same (substrate carrer board) same (heating near1 conduit) same (moving movable move moved)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/06 08:57
L11	7	((die chip wafer) with (mounting attached attach attachment bonding bonded)) and ((substrate carrer board) with (moving movable move moved)) and (heating near1 conduit)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/06 08:58
L12	7	((die chip wafer) with (mounting attached attach attachment bonding bonded)) and ((substrate carrer board) with (moving movable move moved)) and (heating near1 conduit) and temperature	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/06 08:57
L13	5287	((die chip wafer) with (mounting attached attach attachment bonding bonded)) and ((substrate carrer board) with (moving movable move moved)) and (heating heated)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/06 08:58
L14	175	6 and 13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/06 08:58
L15	4525	((die chip wafer) with (mounting attached attach attachment bonding bonded)) and ((substrate carrer board) with (moving movable move moved)) and (heating heated) and temperature	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/06 08:58
L16	86	((die chip wafer) with (mounting attached attach attachment bonding bonded)) same ((substrate carrer board) with (moving movable move moved)) same (heating heated) same temperature	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/06 08:59

L17	5	6 and 16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/06 08:59
L18	153	6 and 15	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/06 09:00